| | Type | L # | Hits | Search Text | DBs | Time Stamp |
|---|------|-----|------|-------------|-----|------------|
| 1 | BRS | L2 | 48583 | CMP or "chemical mechanical polishing" | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/20 11:42 |
| 2 | BRS | L3 | 2008746 | wafer or substrate | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/20 11:42 |
| 3 | BRS | L4 | 11062 | "polishing pad" | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/20 11:42 |
| 4 | BRS | L5 | 12403 | remov$6 adj rate | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/20 11:42 |
| 5 | BRS | L6 | 1760 | conditioning near4 pad | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/20 11:43 |

| | Type | L # | Hits | Search Text | DBs | Time Stamp |
|---|---|---|---|---|---|---|
| 6 | BRS | L7 | 1174125 | calculate ot calculated or calculating | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/20 11:44 |
| 7 | BRS | L8 | 2396721 | rotate or rotating or rotated | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/20 11:44 |
| 8 | BRS | L9 | 491 | 2 and 3 and 4 and 5 and 6 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/20 11:46 |
| 9 | BRS | L10 | 95 | 9 and 7 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/20 12:26 |
| 10 | IS&R | L11 | 1136 | (438/689).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/20 12:26 |

| | Type | L # | Hits | Search Text | DBs | Time Stamp |
|---|---|---|---|---|---|---|
| 11 | IS&R | L12 | 650 | (438/691).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/20 12:26 |
| 12 | IS&R | L13 | 1906 | (438/692).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/08/20 12:26 |